#### Investigation of High Temperature Thermoelectric Materials

#### Research Progress and Prospects for Completion Jack Simonson





## Outline

- Review of Themoelectricity
- XNiSn-type Half-Heusler Dopant Electronic Structure Investigation
- Rare Earth Telluride high-temperature thermoelectrics

## Thermoelectricity



$$\gamma = \lim_{\Delta T \to 0} \frac{\Delta Q}{I \Delta T} = T \frac{dS}{dT}$$

#### Thermoelectric Efficiency for Power Generation

• Dimensionless Figure of Merit:

$$ZT = \frac{S^2 T}{\rho \kappa}$$

• ZT is a measure of efficiency. A ZT of zero indicates no power generation, and a ZT of infinity is Carnot Efficiency.

$$\eta = \frac{T_{H} - T_{C}}{T_{H}} \frac{\sqrt{1 + 2T} - 1}{\sqrt{1 + 2T} + \frac{T_{C}}{T_{H}}}$$



#### Thermoelectric Devices Power Generation

- P-type leg and n-type leg
- Segmented for greater efficiency.
- Compatible currents



#### Semiconductors as Thermoelectrics

- The best thermoelectric materials are semiconductors.
- Gap at Fermi energy allows preferential flow of one carrier type.
- N-type: electron flow in conduction band
- P-type: hole flow on valence band.
- A sharp gap gives the best results.



## Why half-Heusler?



- High symmetry: low resistivity, degenerate bands
- Three sites: options for doping & isoelectronic substitution.
- Three semiconducting compounds
- The downside: high thermal conductivity.



#### Electronic Structure of MNiSn



- For ZrNiSn: Zr and Ni
  bands form the gap
- Sn bands have nothing to do with gap formation – Sn site can be doped
   without interfering with the gap.
- The same is true for MCoSb-type and VFeSb-type
   materials.

#### **KKR-CPA-LDA** Calculations



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### Cartoon Model of Dopant Effects on XNiSn Bandstructure

- Transition metal dopants: V, Cr, Mn, Fe, Co, Ni, Cu on either the Hf/Zr or Ni site.
- Result: creation of dopant band in gap.
- Location determined by high-temperature electrical resistivity



#### High Temperature Electrical Resistivity Curve Fitting

Composition	Gap Size (eV)	
ZrNiSn (theoretical)	0.50-0.51	
HfNiSn (theoretical)	0.48	0.0014
Hf Zr NiCo	0.22	0.00138 -
H10.75 <sup>2</sup> 10.25 <sup>1</sup> 1311	0.25	0.00136 -
$Hf_{0.75}Zr_{0.25}Co_{0.05}Ni_{0.95}Sn$	0.40	0.00134 -
(Hf <sub>0.75</sub> Zr <sub>0.25</sub> ) <sub>0.95</sub> Co <sub>0.05</sub> NiSn	0.47	
	0.07	0.00132 -
Ht <sub>0.75</sub> Zr <sub>0.25</sub> Fe <sub>0.05</sub> NI <sub>0.95</sub> Sn	0.27	<b>ୂ</b> 0.0013 -
Hf <sub>0.75</sub> Zr <sub>0.25</sub> Mn <sub>0.1</sub> Ni <sub>0.9</sub> Sn	0.27	드 욧 0.00128 -
(Hf <sub>0.75</sub> Zr <sub>0.25</sub> ) <sub>0.9</sub> Mn <sub>0.1</sub> NiSn	0.27	
(Hf <sub>0.75</sub> Zr <sub>0.25</sub> ) <sub>0.9</sub> Mn <sub>0.2</sub> Ni <sub>0.9</sub> Sn	0.33	0.00126 -
Lif Zr Cr Ni Cr	0.19	0.00124 -
$Hf_{2} = 2r_{2} = V_{2} \cdot Ni_{2} \cdot Sn$	0.10	0.00122 -
0.25 0.1 0.9	0.10	

0.0012

0.00118 -



#### Thermoelectric, Resistivity, and Hall Measurements



	( <u>µ</u> ∀/K)	(μΩ·cm)		Concentration (cm <sup>-3</sup> )
Hf <sub>0.75</sub> Zr <sub>0.25</sub> Ni Sn	-213	6800	Electrons	$5.5 \times 10^{19}$
Hf <sub>0.75</sub> Zr <sub>0.25</sub> Ni <sub>0.99</sub> Cu <sub>0.01</sub> Sn	-71	1700	Electrons	$2.2 \times 10^{20}$
(Hf <sub>0.75</sub> Zr <sub>0.∞</sub> ) <sub>099</sub> Cu <sub>0.01</sub> Ni Sn	-171	1480		
Hf <sub>0.75</sub> Zr <sub>0.25</sub> Co <sub>0.05</sub> Ni <sub>0.95</sub> Sn	36	6700	Holes	$3.1 \times 10^{20}$
Hf <sub>0.75</sub> Zr <sub>0.25</sub> Co <sub>0.15</sub> Ni <sub>0.85</sub> Sn	56	3800	Holes	$7.3 \times 10^{20}$
(Hf <sub>0.75</sub> Zr <sub>0.25</sub> ) <sub>097</sub> Co <sub>0.18</sub> Ni <sub>0.85</sub> Sn	25	4420		
Hf <sub>0.75</sub> Zr <sub>0.25</sub> Fe <sub>0.05</sub> Ni <sub>0.95</sub> Sn	-86	6750	Electrons	Obscured by magnetic effects
hf <sub>0.75</sub> Zr <sub>0.25</sub> Mn <sub>0.1</sub> Ni <sub>09</sub> Sn	-172	7050	Electrons	$5.4 \times 10^{19}$
(Hf <sub>0.75</sub> Zr <sub>0.25</sub> )09Mn <sub>0.1</sub> Ni Sn	-201	8000	Electrons	$4.1 \times 10^{19}$
n (Hf <sub>0.75</sub> Zr <sub>0.25</sub> )09Mn <sub>0.2</sub> Ni	-195	4000		
Hf <sub>0.75</sub> Zr <sub>0.25</sub> Cr <sub>0.1</sub> Ni <sub>0.9</sub> Sn	-100	2645		
Hf <sub>0.75</sub> Zr <sub>0.25</sub> V <sub>0.1</sub> Ni <sub>09</sub> Sn	-129	2370	Electrons	$2.6 \times 10^{20}$
(Hf <sub>0.75</sub> Zr <sub>0.∞</sub> ) <sub>09</sub> V <sub>0.1</sub> NiSn	-161	4900		
(Hf <sub>0.75</sub> Zr <sub>0.四</sub> )09 <sup>Ce</sup> 0.1 <sup>Ni Sn</sup>	-36	2300		

## Transition Metal Doping in XNiSn: Analysis

• Transition metal doping on the X or Ni site has two effects:

- 1: Lowers thermopower by placing the Fermi energy in a partially unfilled DOS location.
- 2: Dopes inefficiently. The dopant bands are not fully part of the conduction band.
- Transition metal doping is detrimental to high ZT. Lesson learned: future doping efforts must be sp-type only.

#### Why Rare Earth Sesquichalcogenides?

- Semiconducting
- High melting points
- Self-doping and highly sensitive
- Low thermal conductivities
- Good results (ZT=1.5) reported by JPL in 1980s.

# Why La<sub>3-x</sub>Te<sub>4</sub>? (Or LaTe<sub>y</sub>)

- Continuous series of solid solutions for 1.33 < y < 1.50
- All have Th<sub>3</sub>P<sub>4</sub> structure
- Wide range of carrier concentration from 0 to 4.5 x 10<sup>21</sup>/cm<sup>3</sup>
- Low sublimation rate
- Coefficient of thermal expansion matches p-type Zintl Yb<sub>14</sub>MnSb<sub>11</sub>



# LaTe<sub>y</sub> Self-doping

- La<sub>3-x</sub>Te<sub>4</sub> is n-type material
  =>
  (La<sup>+3</sup>)<sub>3-x</sub>V<sub>x</sub>Te<sup>-2</sup><sub>4</sub>e<sup>-1</sup><sub>1-3x</sub>
- When x=0, one free electron/F.U.
- When x =1/3, no free electrons.
- $La_{3-1/3}Te_4 = La_{2/3}Te_4 = La_2Te_3$
- Carrier concentration: n=n<sub>max</sub>(1-3x)



# Comparison: Recent JPL data and our data



# Comparison: Recent JPL data and our data

#### Caltech/JPL

**Uva/Clemson** 



# Comparison: Recent JPL data and our data



## LaTe<sub>y</sub> at Intermediate Temperature

Thermopower

Resistivity



# LaTe<sub>y</sub> Challenges

- LaTe<sub>y</sub> has significant Te evaporation during melting. Sample stoichiometry must be improved.
- Oxidation occurs during initial reaction and ball milling.
- Obtaining a solid sample challenging. LaTe<sub>y</sub> reaction is exothermic.
- Find better method for High Temperature measurement.

#### Future Work

- Suction casting to constrain LaTe<sub>y</sub> and form solid samples – will improve resistivity.
- Begin looking at dopants/substitutions to minimize thermal conductivity, possibly improve electronic properties.

### Dopant band formation: Ti<sub>1-x</sub>Mn<sub>x</sub>NiSn

- Ti vacancy depletes 4 electrons, Mn adds 7.
- Ti levels tend to be above gap, Ni tend to be below. Larger nuclei pull electrons to lower energy.



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## High-Symmetry Points for F-43m



#### Electronic Structure of TiCoSb

